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| U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified) | | | | Docket No. | Serial No. |
| NOV. 21 2003 | | | | AMAT/2592.C6/DSM /LOW K JW | 10/632,179 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | | | Applicant Xia, et al. | Confirmation No. Unknown |
| (Use several sheets if necessary) | | | | Filing Date | Group |
| | Examiner Unknown | | | July 31, 2003 | Unknown |

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| | B3 | 6-168937 | 06/14/1994 | JP (Abstract) | HOIL | 21/316 | <input checked="" type="checkbox"/> | <input type="checkbox"/> |
| | B4 | 8-222559 | 08/30/1996 | JP (Abstract) | HOIL | 21/316 | <input checked="" type="checkbox"/> | <input type="checkbox"/> |
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

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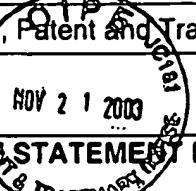
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| | B23 | 0 849 789 A2 | 06/24/1998 | EP | H01L | 21/311 | <input type="checkbox"/> | <input checked="" type="checkbox"/> |
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| | B25 | 196 54 737 A1 | 07/03/1997 | GERMANY | HOIL | 21/31 | <input checked="" type="checkbox"/> | <input type="checkbox"/> |
| <i>D2</i> | B26 | 198 04 375 A1 | 01/07/1999 | GERMANY | HOIL | 21/312 | <input type="checkbox"/> | <input checked="" type="checkbox"/> |

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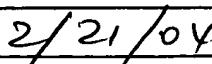
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|  NOV 21 2003 | | | | | AMAT/2592.C6/DSM /LOW K JW | | 10/632,179 | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | | | | Applicant | | Confirmation No. | |
| | | | | | Xia, et al. | | Unknown | |
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| Examiner | <i>Sam R.</i> | | | | Date Considered | | | 2/21/04 |
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| U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified) | | Docket No. AMAT/2592.C6/DSM /LOW K JW | Serial No. 10/632,179 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | Applicant Xia, et al. | Confirmation No. Unknown |
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